

ABSTRACT

ADHESIVE SHEET FOR PRODUCING SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE, AND PRODUCTION METHOD FOR
SEMICONDUCTOR DEVICE

An object of the present invention is to provide an adhesive sheet for producing a semiconductor device, which can prevent the generation of out gas components which is caused by using a silicone adhesive and the like, and the occurrence of adhesive transfer
5 while maintaining excellent wire bonding properties and mold flash properties of thermosetting adhesives when the adhesive sheet is used for producing a semiconductor device such as a QFN, and can thereby prevent the production of defective semiconductor devices, in order to achieve the object, the present invention provide an adhesive sheet for producing a semiconductor device which is detachably attached to a lead frame or a
10 wiring substrate, wherein the adhesive sheet comprises a substrate and an adhesive layer, and the adhesive layer comprises a thermosetting resin component (a), a thermoplastic resin component (b), and a fluorine based additive (c).

Figure : None